

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT2700619

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HUNG-CHUAN PAI	11/30/2013
RECEIVING PARTY DATA	
Name:	MStar Semiconductor, Inc.
Street Address:	4F-1, No. 26, Tai-Yuan Street
Internal Address:	ChuPei
City:	Hsinchu Hsien
State/Country:	TAIWAN
Postal Code:	302
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14107478
CORRESPONDENCE DATA	
Fax Number:	(301)762-4056
Phone:	301-424-3640
Email:	kew@usiplaw.com
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>	
Correspondent Name:	EDELL, SHAPIRO & FINNAN, LLC
Address Line 1:	LAWRENCE D. EISEN
Address Line 2:	9801 WASHINGTONIAN BLVD., SUITE 750
Address Line 4:	GAITHERSBURG, MARYLAND 20878
ATTORNEY DOCKET NUMBER:	0470.0187C (MST0761-US)
NAME OF SUBMITTER:	LAWRENCE D. EISEN
Signature:	/Lawrence D. Eisen/
Date:	01/28/2014
Total Attachments: 1 source=ExecutedAssn#page1.tif	

**ASSIGNMENT**

For good and valuable consideration, I/WE, Hung-Chuan Pai, a citizen of the United States of America, residing at 26 Gazebo, Irvine, CA 92620, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to **MStar Semiconductor, Inc.**, having its principal place of business at 4F-1, Number 26 Tai-Yuan Street ChuPei, Hsinchu Hsien 302, Taiwan R.O.C., hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and

entitled: **BROADBAND SINGLE-ENDED INPUT TO DIFFERENTIAL OUTPUT  
LOW-NOISE AMPLIFIER**

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE:  DATE: 11/30/2013  
Hung-Chuan Pai